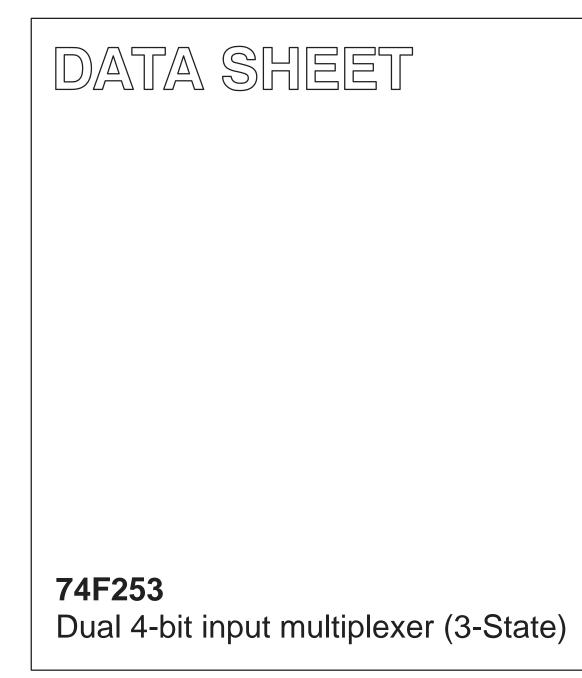
# INTEGRATED CIRCUITS



Product specification

1988 Nov 29

IC15 Data Handbook



HILIP

Philips Semiconductors

### 74F253

### **FEATURES**

- 3-State outputs for bus interface and multiplex expansion
- Common select inputs
- Separate Output Enable Inputs

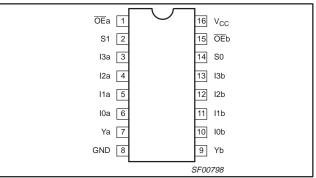
### DESCRIPTION

The 74F253 has two identical 4-input multiplexers with 3-State outputs which select two bits from four sources selected by common Select inputs (S0, S1). When the individual Output Enable ( $\overline{OEa}$ ,  $\overline{OEb}$ ) inputs of the 4-input multiplexers are High, the outputs are forced to a high impedance (Hi-Z) state.

The 74F253 is the logic implementation of a 2-pole, 4-position switch; the position of the switch being determined by the logic levels supplied to the two common Select inputs.

To avoid exceeding the maximum current ratings when the outputs of the 3-State devices are tied together, all but one device must be in the high-impedance state. Therefore, only one Output Enable must be active at a time.

### **PIN CONFIGURATION**



TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F253	7.0ns	12mA

### **ORDERING INFORMATION**

	COMMERCIAL RANGE	
DESCRIPTION	V <sub>CC</sub> = 5V ±10%, T <sub>amb</sub> = 0°C to +70°C	PKG DWG #
16-pin plastic DIP	N74F253N	SOT38-4
16-pin plastic SO	N74F253D	SOT109-1

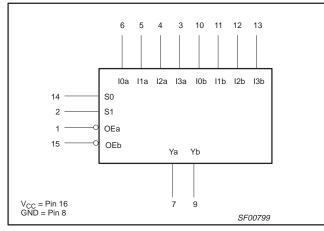
### INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
10a–13a	Port A data inputs	1.0/1.0	20µA/0.6mA
l0b–l3b	Port B data inputs	1.0/1.0	20µA/0.6mA
S0, S1	Common Select inputs	1.0/1.0	20µA/0.6mA
OEa	Port A Output Enable input (active Low)	1.0/1.0	20µA/0.6mA
OEb	Port B Output Enable input (active Low)	1.0/1.0	20µA/0.6mA
Ya, Yb	3-State outputs	150/40	3mA/24mA

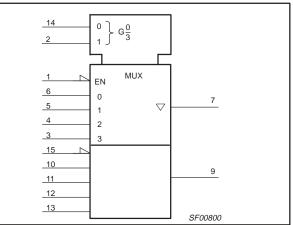
#### NOTE:

One (1.0) FAST unit load is defined as: 20µA in the High state and 0.6mA in the Low state.

### LOGIC SYMBOL

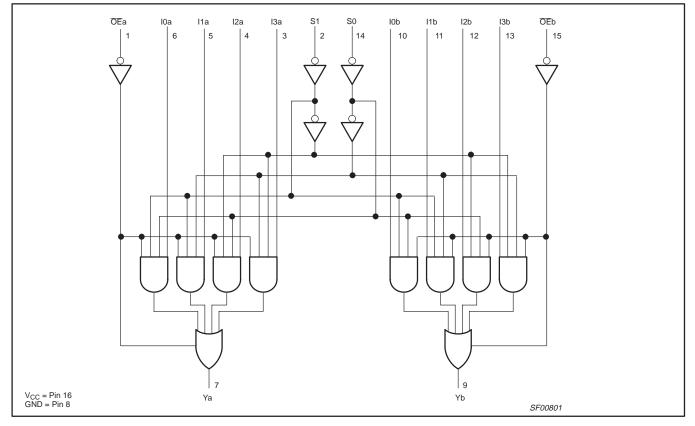


### **IEC/IEEE SYMBOL**



### 74F253

### LOGIC DIAGRAM



### **FUNCTION TABLE**

			INPUTS				OUTPUT
S0	S1	10	11	12	13	ŌĒ	Y
Х	Х	Х	Х	Х	Х	Н	Z
L	L	L	Х	Х	Х	L	L
L	L	н	Х	Х	Х	L	Н
н	L	х	L	х	х	L	L
н	L	х	Н	х	х	L	Н
L	н	х	х	L	Х	L	L
L	н	х	х	н	Х	L	Н
н	н	х	х	х	L	L	L
н	н	х	Х	х	Н	L	Н

NOTES:

H = High voltage level L = Low voltage level X = Don't care Z = High impedance "off" state

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#### **ABSOLUTE MAXIMUM RATINGS**

(Operation beyond the limit set forth in this table may impair the useful life of the device.

Unless otherwise noted these limits are over the operating free air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V <sub>CC</sub>	Supply voltage	-0.5 to +7.0	V
V <sub>IN</sub>	Input voltage	-0.5 to +7.0	V
I <sub>IN</sub>	Input current	-30 to +5	mA
V <sub>OUT</sub>	Voltage applied to output in High output state	–0.5 to $V_{CC}$	V
I <sub>OUT</sub>	Current applied to output in Low output state	48	mA
T <sub>amb</sub>	Operating free-air temperature range	0 to +70	°C
T <sub>stg</sub>	Storage temperature	-65 to +150	°C

### **RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER		LIMITS		UNIT
STWBOL	PARAMETER	MIN	NOM	MAX	UNIT
V <sub>CC</sub>	Supply voltage	4.5	5.0	5.5	V
V <sub>IH</sub>	High-level input voltage	2.0			V
V <sub>IL</sub>	Low-level input voltage			0.8	V
I <sub>IK</sub>	Input clamp current			-18	mA
I <sub>OH</sub>	High-level output current			-3	mA
I <sub>OL</sub>	Low-level output current			24	mA
T <sub>amb</sub>	Operating free-air temperature range	0		70	°C

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### DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

							LIMITS		
SYMBOL	PARAMETE	R	TEST COND	TEST CONDITIONS <sup>NO TAG</sup>					UNIT
M			$V_{CC} = MIN, V_{IL} = MAX,$	±10%V <sub>CC</sub>	2.4			V	
V <sub>OH</sub>	High-level output voltage	;	$V_{IH} = MIN, I_{OH} = MAX$		±5%V <sub>CC</sub>	2.7	3.3		V
M			$V_{CC} = MIN, V_{IL} = MAX,$		±10%V <sub>CC</sub>		0.35	0.50	V
V <sub>OL</sub>	Low-level output voltage		$V_{IH} = MIN, I_{OL} = MAX$		±5%V <sub>CC</sub>		0.35	0.50	V
V <sub>IK</sub>	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$		-0.73	-1.2	V		
lı	Input current at maximur voltage	n input	$V_{CC} = MAX, V_I = 7.0V$			100	μA		
I <sub>IH</sub>	High-level input current		$V_{CC} = MAX, V_1 = 2.7V$			20	μA		
I <sub>IL</sub>	Low-level input current		$V_{CC} = MAX, V_I = 0.5V$			-0.6	mA		
I <sub>OZH</sub>	Off-state output current High-level voltage applie	d	$V_{CC} = MAX, V_O = 2.7V$			50	μA		
I <sub>OZL</sub>	Off-state output current Low-level voltage applie	d	$V_{CC} = MAX, V_{O} = 0.5V$	$V_{CC} = MAX, V_O = 0.5V$					μA
I <sub>OS</sub>	Short-circuit output curre	ent <sup>NO TAG</sup>	V <sub>CC</sub> = MAX					-150	mA
		I <sub>CCH</sub>		OEn=GND, S	OEn=GND, Sn=In=4.5V		10	16	mA
I <sub>CC</sub>	Supply current (total)	I <sub>CCL</sub>	V <sub>CC</sub> = MAX OEn=Sn=In=GND				12	23	mA
		I <sub>CCZ</sub>	]	0En=4.5V, S	Sn=In=GND		14	23	mA

NOTES:

1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

2. All typical values are at  $V_{CC} = 5V$ ,  $T_{amb} = 25^{\circ}C$ . 3. Not more than one output should be shorted at a time. For testing  $I_{OS}$ , the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.

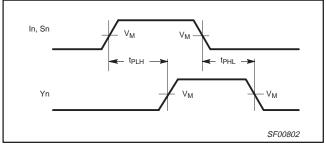
74F253

### **AC ELECTRICAL CHARACTERISTICS**

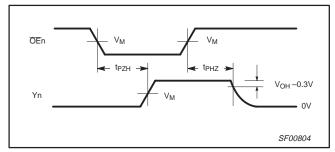
				LIMITS								
SYMBOL	PARAMETER	TEST CONDITION	T,	V <sub>CC</sub> = +5V <sub>amb</sub> = +25° C <sub>L</sub> = 50pF R <sub>L</sub> = 500Ω	C	V <sub>CC</sub> = +5 T <sub>amb</sub> = 0°C C <sub>L</sub> = R <sub>L</sub> =	UNIT					
			MIN	TYP	MAX	MIN	MAX					
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay In to Yn	Waveform NO TAG	3.0 3.0	4.5 5.0	7.0 7.0	3.0 3.0	7.5 8.0	ns				
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay Sn to Yn	Waveform NO TAG	4.5 5.0	7.5 8.5	10.5 11.0	4.5 4.5	11.0 12.0	ns				
t <sub>PZH</sub> t <sub>PZL</sub>	Output Enable time to High or Low level	Waveform 2 Waveform 3	3.0 3.0	6.5 6.5	8.0 8.0	3.0 3.0	9.0 9.0	ns				
t <sub>PHZ</sub> t <sub>PLZ</sub>	Output Disable time from High or Low level	Waveform 2 Waveform 3	2.5 2.0	3.5 3.0	5.0 5.0	2.0 1.5	6.0 6.0	ns				

### AC WAVEFORMS

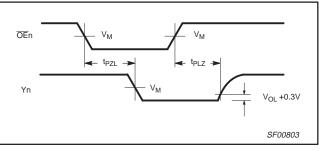
For all waveforms,  $V_{M}$  = 1.5V



Waveform 1. Propagation Deley, Data and Select to Output



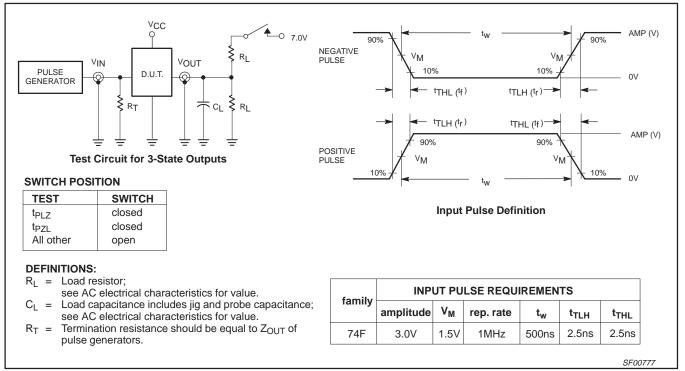
Waveform 2. 3-State Output Enable Time to High Level and Output Disable Time from High Level

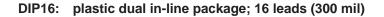


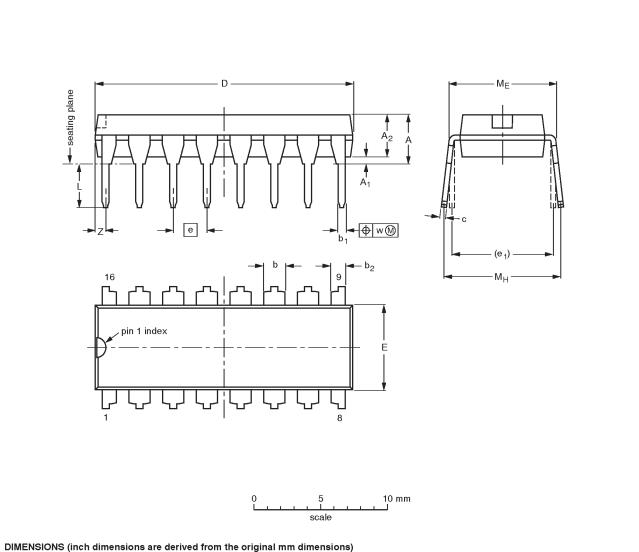
Waveform 3. 3-State Output Enable Time to Low Level and Output Disable Time from Low Level

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### **TEST CIRCUIT AND WAVEFORMS**







UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	b <sub>2</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	e <sub>1</sub>	L	M <sub>E</sub>	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	1.25 0.85	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	0.76
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.049 0.033	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.030

#### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT38-4						<del>-92-11-17</del> 95-01-14

74F253

SOT38-4

SO16: plastic small outline package; 16 leads; body width 3.9 mm

16

	0	2.5	5 mm
		scale	
limensions are derived from the o	riginal	mm dimensior	ıs)

# DIMENSIONS (inch dime

U	NIT	max.	A <sub>1</sub>	A <sub>2</sub>	Α3	<b>b</b> р	с	D <sup>(1)</sup>	E <sup>(1)</sup>	е	Η <sub>E</sub>	L	Lp	Q	v	w	У	Z <sup>(1)</sup>	θ
n	nm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inc	ches	0.069	0.010 0.004	0.057 0.049	0.01			0.39 0.38	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	0 <sup>0</sup>

#### Note

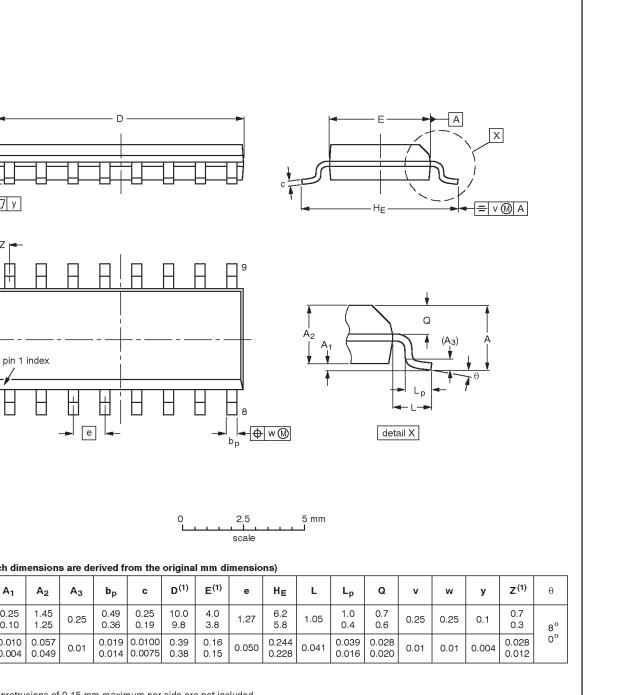
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN	ISSUE DATE
	IEC	JEDEC	EIAJ		PROJECTION	1550E DATE
SOT109-1	076E07S	MS-012AC				<del>-95-01-23</del> 97-05-22

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### 74F253

SOT109-1



### 74F253

#### Data sheet status

Data sheet status	Product status	Definition [1]	
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.	
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later d Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.	
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to mak changes at any time without notice in order to improve design and supply the best possible pro-	

[1] Please consult the most recently issued datasheet before initiating or completing a design.

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